MARKING DIAGRAMS

### TinyLogic UHS Two-Input NOR Gate

### NC7SZ02

#### Description

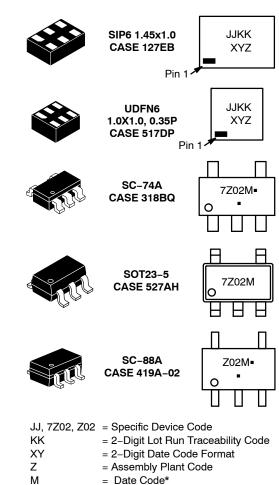
The NC7SZ02 is a single two-input NOR gate from **onsemi**'s Ultra-High Speed (UHS) series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{CC}$  operating range. The inputs and output are high-impedance when  $V_{CC}$  is 0 V. Inputs tolerate voltages up to 5.5 V, independent of  $V_{CC}$  operating range.

#### Features

- Ultra-High Speed:  $t_{PD}$  = 2.4 ns (Typical) into 50 pF at 5 V V<sub>CC</sub>
- High Output Drive:  $\pm 24$  mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V<sub>CC</sub>
- Power Down High-Impedance Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra–Small MicroPak<sup>TM</sup> Packages
- Space-Saving SOT23-5, SC-74A and SC-88A Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol



= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

#### **Pin Configurations**

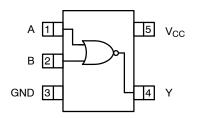


Figure 2. SOT23-5, SC-88A and SC-74A (Top View)

#### **PIN DEFINITIONS**

Pin # SOT23–5, SC–88A / SC74A	Pin # MicroPak	Name	Description
1	1	А	Input
2	2	В	Input
3	3	GND	Ground
4	4	Y	Output
5	6	V <sub>CC</sub>	Supply Voltage
	5	NC	No Connect

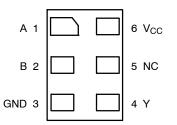


Figure 3. MicroPak (Top Through View)

#### **FUNCTION TABLE**

Inp	Output	
А	В	Y
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	6.5	V
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Current		-	±50	mA
$I_{CC} \text{ or } I_{GND}$	DC V <sub>CC</sub> or Ground Current		-	±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bias		-	+150	°C
ΤL	Junction Lead Temperature (Sold	ering, 10 Seconds)	-	+260	°C
PD	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	
		MicroPak-6	-	812	
		MicroPak2 <sup>™</sup> –6	-	812	
ESD	Human Body Model, JEDEC: JESD22-A114		-	4000	V
	Charge Device Model, JEDEC: JE	ESD22-C101	-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Мах	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	$V_{CC}$ at 1.8 V, 2.5 V $\pm 0.2$ V	0	20	ns/V
		$V_{CC}$ at 3.3 V $\pm 0.3$ V	0	10	
		$V_{CC}$ at 5.0 V $\pm 0.5$ V	0	5	
$\theta_{JA}$	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	
		MicroPak2-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 1. Unused inputs must be held HIGH or LOW. They may not float.



### NC7SZ02

#### DC ELECTICAL CHARACTERISTICS

				T <sub>A</sub> = +25°C			T <sub>A</sub> = −40 to +85°C			
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit	
VIH	HIGH Level Input Voltage	1.65 to 1.95		0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	-	V	
		2.30 to 5.50		0.70 V <sub>CC</sub>	-	-	0.70 V <sub>CC</sub>	_		
V <sub>IL</sub>	LOW Level Input Voltage	1.65 to 1.95		-	-	0.35 V <sub>CC</sub>	_	0.35 V <sub>CC</sub>	V	
		2.30 to 5.50		-	-	0.30 V <sub>CC</sub>	-	0.30 V <sub>CC</sub>		
V <sub>OH</sub>	HIGH Level Output Voltage	1.65	$V_{IN} = V_{IH} \text{ or } V_{IL},$	1.55	1.65	-	1.55	_	V	
		1.80	I <sub>OH</sub> = −100 μA	1.70	1.80	-	1.70	_		
		2.30		2.20	2.30	-	2.20	_		
		3.00		2.90	3.00	-	2.90	-		
		4.50		4.40	4.50	-	4.40	_		
		1.65	I <sub>OH</sub> = -4 mA	1.29	1.52	-	1.29	_		
		2.30	I <sub>OH</sub> = -8 mA	1.90	2.15	-	1.90	_		
		3.00	I <sub>OH</sub> = -16 mA	2.40	2.80	-	2.40	_		
	3.00	I <sub>OH</sub> = -24 mA	2.30	2.68	-	2.30	_			
		4.50	I <sub>OH</sub> = -32 mA	3.80	4.20	-	3.80	_		
V <sub>OL</sub>	LOW Level Output Voltage	1.65	$V_{IN} = V_{IH}$ or $V_{IL}$ ,	-	0.00	0.10	_	0.10	V	
		1.80	I <sub>OL</sub> = 100 μA	-	0.00	0.10	-	0.10	1	
		2.30		-	0.00	0.10	-	0.10		
		3.00		-	0.00	0.10	-	0.10		
		4.50		-	0.00	0.10	-	0.10		
		1.65	I <sub>OL</sub> = 4 mA	-	0.08	0.24	-	0.24		
		2.30	I <sub>OL</sub> = 8 mA	-	0.10	0.30	-	0.30		
		3.00	I <sub>OL</sub> = 16 mA	-	0.15	0.40	-	0.40		
		3.00	I <sub>OL</sub> = 24 mA	-	0.22	0.55	-	0.55		
		4.50	I <sub>OL</sub> = 32 mA	-	0.22	0.55	-	0.55		
I <sub>IN</sub>	Input Leakage Current	1.65 to 5.50	V <sub>IN</sub> = 5.5 V, GND	-	-	±1	-	±10	μA	
I <sub>OFF</sub>	Power Off Leakage Current	0	$V_{IN}$ or $V_{OUT}$ = 5.5 V	-	-	1	-	10	μA	
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> = 5.5 V, GND	-	-	2.0	-	20	μA	



#### NC7SZ02

#### AC ELECTRICAL CHARACTERISTICS

				$T_{A} = +25^{\circ}C$ $T_{A} = -40$ to		to +85°C			
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub> Propagation Delay	1.65	C <sub>L</sub> = 15 pF,	-	5.3	11.5	-	12.0	ns	
	(Figure 4, 5)	1.80	$R_L = 1 M\Omega$	-	4.4	9.5	-	10.0	
		2.50 ±0.20		-	2.9	6.5	-	7.0	
		3.30 ±0.30		-	2.3	4.5	-	4.7	
		5.00 ±0.50		-	1.9	3.9	-	4.1	
		3.30 ±0.30	C <sub>L</sub> = 50 pF,	-	2.9	5.0	-	5.2	
		5.00 ±0.50	R <sub>L</sub> = 500 Ω	-	2.4	4.3	-	4.5	
C <sub>IN</sub>	Input Capacitance	0		-	4	-	-	-	pF
C <sub>PD</sub>	C <sub>PD</sub> Power Dissipation Capacitance (Note 2) (Figure 6)	3.30		-	23	-	-	-	pF
		5.00	1	-	30	_	-	_	

2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle.  $C_{PD}$  is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = ( $C_{PD}$ ) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).

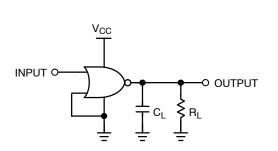


Figure 4. AC Test Circuit

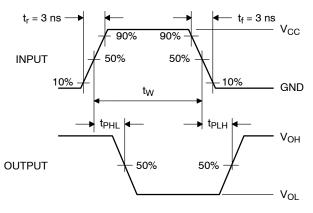
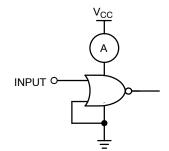


Figure 5. AC Waveforms





3. Input = AC Waveform;  $t_r = t_f = 1.8$  ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I<sub>CC</sub>D Test Circuit



#### **ORDERING INFORMATION**

Part Number	Top Mark	Packages	Shipping <sup>†</sup>
NC7SZ02M5X	7Z02	SC-74A	3000 / Tape & Reel
NC7SZ02P5X	Z02	SC-88A	3000 / Tape & Reel
NC7SZ02L6X	JJ	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ02FHX	JJ	UDFN6, MicroPak2	5000 / Tape & Reel

#### **DISCONTINUED** (Note 4)

NC7SZ02M5X-L22090	7Z02	SOT23-5	3000 / Tape & Reel
NC7SZ02L6X-L22175	IJ	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ02FHX-L22175	JJ	UDFN6, MicroPak2	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

4. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <u>www.onsemi.com</u>.

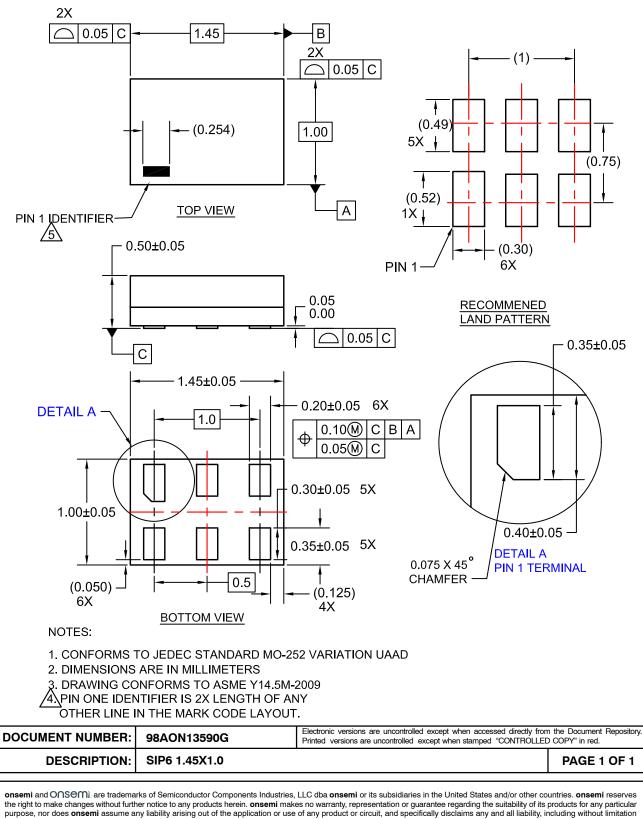
MicroPak and MicroPak2 are trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.





SIP6 1.45X1.0 CASE 127EB ISSUE O

DATE 31 AUG 2016



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#### SC-74A-5 3.00x1.50x0.95, 0.95P CASE 318BQ **ISSUE C** DATE 26 FEB 2024 NOTES: 5X b ⊕ 0.20 M C A B DIMENSIONING AND TOLERANCING CONFORM TO ASME 1. Y14.5-2018. 2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES). В 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, Ē 4 E1 PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. MILLIMETERS ○ 0.15 C DIM NOM. MIN. MAX. 2X е 0.90 1.00 1.10 А A A1 0.01 0.18 0.10 0.95 REF Α2 TOP VIEW 0.25 0.37 0.50 b DETAIL A (A2) 0.10 0.18 0.26 С Α D 2.85 3.00 3.15 Ε 2.75 BSC E1 1.35 1.50 1.65 0.05 C SEATING е 0.95 BSC Α1 Ċ PLANE END VIEW SIDE VIEW L 0.20 0.40 0.60 L1 0.62 REF 0.25 BSC 12 GAUGE PLANE L2 5° 10° Θ 0° 1.90 0.95 Ð, (L1)"A" DETAIL SCALE 2:1 2.40 GENERIC **MARKING DIAGRAM\*** 1.00 0.70 XXX M= -O RECOMMENDED MOUNTING FOOTPRINT\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING XXX = Specific Device Code = Date Code Μ TECHNIQUES REFERENCE MANUAL, SOLDERRM/D. = Pb-Free Package (Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •" may or may not be present. Some products may not follow the Generic Marking. Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON66279G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SC-74A-5 3.00x1.50x0.95, 0.95P PAGE 1 OF 1

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DATE 11 APR 2023



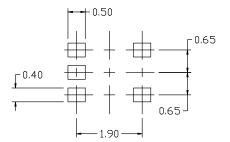
#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE. NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

e

E1



#### RECOMMENDED MOUNTING FOOTPRINT

 For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DIM	MILLIMETERS				
MIU	MIN.	NDM.	MAX,		
А	0.80	0.95	1.10		
A1			0.10		
AЗ	0.20 REF				
b	0.10	0.20	0.30		
C	0.10		0.25		
D	1.80	2.00	2.20		
E	2.00	2.10	2.20		
E1	1.15	1.25	1.35		
e	0.65 BSC				
L	0.10	0.15	0.30		

#### **GENERIC MARKING**





\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

DESCRIPTION:	SC-88A (SC-70-	5/SOT-353)			PAGE 1 OF 1
DOCUMENT NUMBER:	98ASB42984B			t when accessed directly from /hen stamped "CONTROLLED	
4. COLLECTOR 5. COLLECTOR STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE	4. COLLECTOR 5. CATHODE STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR	4. CATHODE 2 5. CATHODE 1 STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	4. GATE 1 5. GATE 2 STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	4. CATHODE 3 5. CATHODE 4 Note: Please refer to style callout. If style t out in the datasheet p datasheet pinout or p	ype is not called refer to the device
STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1	STYLE 5: PIN 1. CATHODE 2. COMMON ANOE 3. CATHODE 2	DE

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UDFN6 1.0X1.0, 0.35P CASE 517DP ISSUE O DATE 31 AUG 2016 0.89 -ン|0.05|C в 1.00±0.050 А 0.35 2X 5X 0.40 PIN 1 MIN 250uM 0.66 1.00±0.050 1X 0.45  $\square$  0.05 C TOP VIEW - 6X 0.19 2X **RECOMMENDED LAND PATTERN** FOR SPACE CONSTRAINED PCB 0.05 C 0.90 -0.35 0.50±0.05 С 5X 0.52 SIDE VIEW 6X 0.14±0.05 (0.08) 4X — 0.73 2 DETAIL A 1 3 1X 0.57 – 0.20 6X ALTERNATIVE LAND PATTERN FOR UNIVERSAL APPLICATION - (0.05) 6X 5X 0.30±0.05 0.60 4 0.10(M) C B A 0.35 (0.08) .05 C 4X 0.35±0.050 BOTTOM VIEW NOTES: A. COMPLIES TO JEDEC MO-252 STANDARD **B. DIMENSIONS ARE IN MILLIMETERS.** C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009 0.075X45° DETAIL A CHAMFER PIN 1 LEAD SCALE: 2X

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DESCRIPTION:	UDFN6 1.0X1.0, 0.35P		PAGE 1 OF 1		

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PIN 1

REFERENCE

#### SOT-23, 5 Lead CASE 527AH ISSUE A

DATE 09 JUN 2021

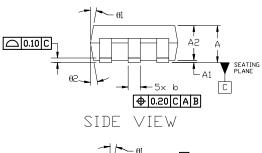


A

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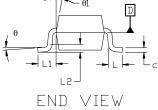
В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.



-e

TOP VIEW



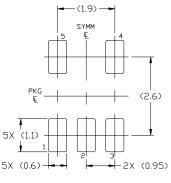
GENERIC MARKING DIAGRAM\*



XXX = Specific Device CodeM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

	MILLIMETERS		
DIM	MIN.	NDM.	MAX.
Α	0.90	—	1.45
A1	0.00	_	0.15
A2	0.90	1.15	1.30
b	0.30	—	0.50
С	0.08	—	0.22
D	2.90 BSC		
E	2.80 BSC		
E1	1.60 BSC		
e	0.95 BSC		
L	0.30	0.45	0.60
L1	0.60 REF		
L2	0.25 REF		
θ	0*	4°	8*
θ1	0*	10°	15°
θ2	0*	10*	15°



#### RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	SOT-23, 5 LEAD		PAGE 1 OF 1	

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